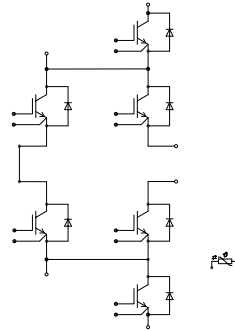
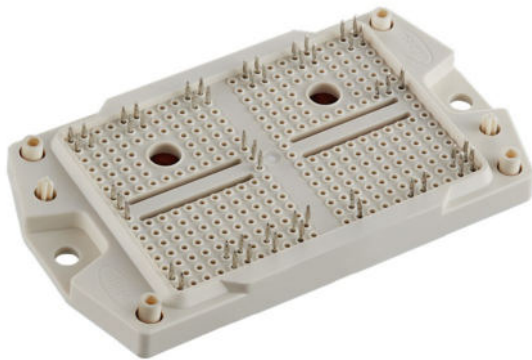


EasyPACK™ Modul mit TRENCHSTOP™ IGBT7 und CoolSiC™ Schottky Diode und PressFIT / NTC
 EasyPACK™ module with TRENCHSTOP™ IGBT7 and CoolSiC™ Schottky diode and PressFIT / NTC



$V_{CES} = 950V$

$I_{C\ nom} = 400A / I_{CRM} = 800A$

Potentielle Anwendungen

- 3-Level-Applikationen
- Solar Anwendungen

Elektrische Eigenschaften

- CoolSiC™ Schottky Diode Gen 5
- Niederinduktives Design
- Niedrige Schaltverluste
- Trenchstop™ IGBT7

Mechanische Eigenschaften

- Gehäuse mit CTI > 400
- Integrierter NTC Temperatur Sensor
- PressFIT Verbindungstechnik

Potential Applications

- 3-level-applications
- Solar applications

Electrical Features

- CoolSiC™ Schottky diode gen 5
- Low inductive design
- Low switching losses
- Trenchstop™ IGBT7

Mechanical Features

- Package with CTI > 400
- Integrated NTC temperature sensor
- PressFIT contact technology

Module Label Code

Barcode Code 128



000001234560000000000000

DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

IGBT, T1 / T4 / IGBT, T1 / T4**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	950	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	400	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	220	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	800	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,40 1,48 1,50	1,60	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 6,50\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	4,35	5,10	5,85 V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 600\text{ V}$		Q_G	0,90		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	0,75		Ω
Eingangskapazität Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	25,2		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,078		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 950\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}		0,071	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,094 0,094 0,094		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,033 0,033 0,033		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,74 0,81 0,82		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,033 0,057 0,07		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 4200\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	4,30 4,30 4,30		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 4600\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	5,00 6,60 7,30		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 600\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{sCE} \cdot di/dt$	$t_P \leq 0\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	1200		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		R_{thJH}	0,240		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

IGBT, T2 / T3 / IGBT, T2 / T3**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	950	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	400	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	295	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	800	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,07 1,04 1,02	1,15	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 6,50\text{ mA}, V_{CE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	4,15	4,90	5,65 V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 600\text{ V}$		Q_G	4,10		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	0,75		Ω
Eingangskapazität Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	49,2		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,228		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 950\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}		0,071	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,21 0,19 0,18		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,034 0,038 0,039		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,85 0,96 0,98		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,24 0,45 0,50		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 4500\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	3,35 3,46 3,49		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 1350\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	24,8 35,6 37,9		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 600\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{sCE} \cdot di/dt$	$t_P \leq 0\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	1200		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		R_{thJH}	0,280		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

IGBT, T5 / T6 / IGBT, T5 / T6**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	950	V
Implementierter Kollektor-Strom Implemented collector current		I_{CN}	200	A
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	115	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	I_{CRM}	400	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		V_{GES}	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,68 1,88 1,92	2,00	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 3,25\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	4,35	5,10	5,85 V
Gateladung Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 600\text{ V}$		Q_G	0,45		μC
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$	1,5		Ω
Eingangskapazität Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}	12,6		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}	0,039		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 950\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}		0,1	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$	0,086 0,093 0,094		μs μs μs
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r	0,027 0,03 0,03		μs μs μs
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 30\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$	0,57 0,615 0,625		μs μs μs
Fallzeit, induktive Last Fall time, inductive load	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 30\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f	0,024 0,052 0,073		μs μs μs
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 4000\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{on}} = 5,0\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}	6,35 7,60 8,00		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 150\text{ A}, V_{CE} = 500\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 5800\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{off}} = 30\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}	5,00 6,30 6,80		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 600\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{\text{SCE}} \cdot di/dt$	$t_P \leq 0\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}	600		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		$R_{th\text{JH}}$	0,451		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

Diode, D1 / D4 / Diode, D1 / D4**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzenspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	950	V
Implementierter Durchlassstrom Implemented forward current		I_{FN}	200	A
Dauergleichstrom Continuous DC forward current		I_F	150	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	400	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1620 1530	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 150\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 150\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 150\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	2,33 2,12 2,08	2,54	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 150\text{ A}, -di_F/dt = 4000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	90,0 130 140		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 150\text{ A}, -di_F/dt = 4000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	5,50 10,0 12,5		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 150\text{ A}, -di_F/dt = 4000\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	1,50 3,30 3,95		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode	R_{thJH}		0,570		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

Diode, D2 / D3 / Diode, D2 / D3**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzenspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	950	V
Implementierter Durchlassstrom Implemented forward current		I_{FN}	200	A
Dauergleichstrom Continuous DC forward current		I_F	150	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	400	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1620 1530	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 150\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 150\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 150\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	2,33 2,12 2,06	2,54	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 150\text{ A}, -di_F/dt = 4500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	133 180 195		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 150\text{ A}, -di_F/dt = 4500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	6,00 13,0 15,5		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 150\text{ A}, -di_F/dt = 4500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	2,40 5,70 6,80		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode	R_{thJH}		0,570		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

Diode, D5-D6 / Diode, D5-D6**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	1200	V
Dauergleichstrom Continuous DC forward current		I_F	100	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	200	A
Grenzlastintegral I^2t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	1650 1550	A^2s A^2s

Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F	1,45 1,75 1,85	1,75	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 3200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}	60,0 60,0 60,0		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 3200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r	1,85 1,85 1,85		μC μC μC
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 3200\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 500\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}	0,68 0,68 0,68		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode		R_{thJH}	0,474		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

NTC-Widerstand / NTC-Thermistor**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	R_{25}		5,00		k Ω
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\text{ }\Omega$	$\Delta R/R$	-5		5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	P_{25}			20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/50}$		3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/80}$		3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/100}$		3433		K

Angaben gemäß gültiger Application Note.

Specification according to the valid application note.

Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	3,2	kV	
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		11,5 6,8	mm	
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		9,4 5,5	mm	
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
Relativer Temperaturindex (elektr.) RTI Elec.	Gehäuse housing	RTI	140	°C	
			min.	typ.	max.
Modulstreuinduktivität Stray inductance module		L _{sCE}		15	nH
Lagertemperatur Storage temperature		T _{stg}	-40		125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube - Montage gem. gültiger Applikationsschrift Screw - Mounting according to valid application note	M	1,30		1,50 Nm
Gewicht Weight		G		78	g

Der Strom im Dauerbetrieb ist auf 25 A effektiv pro Anschlusspin begrenzt.

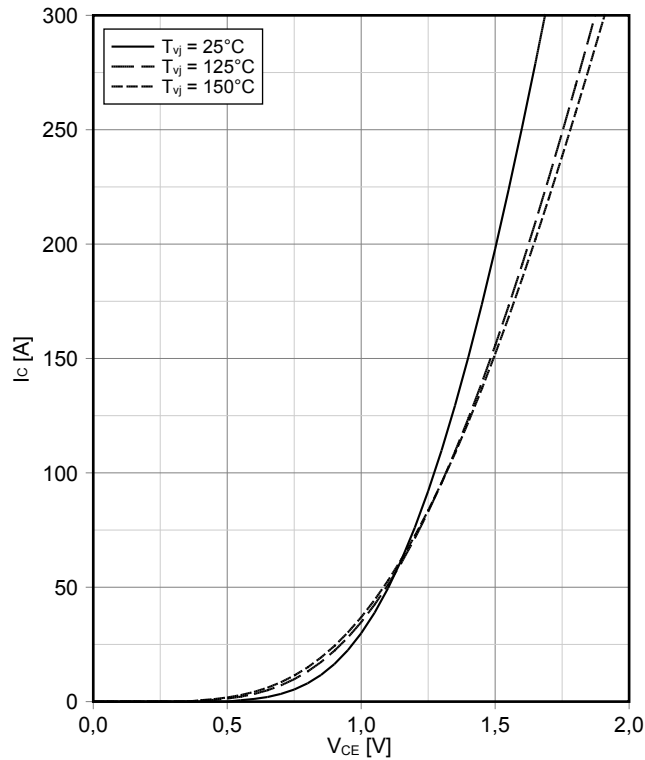
The current under continuous operation is limited to 25 A rms per connector pin.

IGBT- und Dioden-RthJH-Parameter mit einer Wärmeleitpaste $\lambda_{\text{Paste}} = 3.3 \text{ W/(m}\cdot\text{K)}$ gemessen

IGBT- and diode- RthJH parameters measured with thermal grease of $\lambda_{\text{Paste}} = 3.3 \text{ W/(m}\cdot\text{K)}$

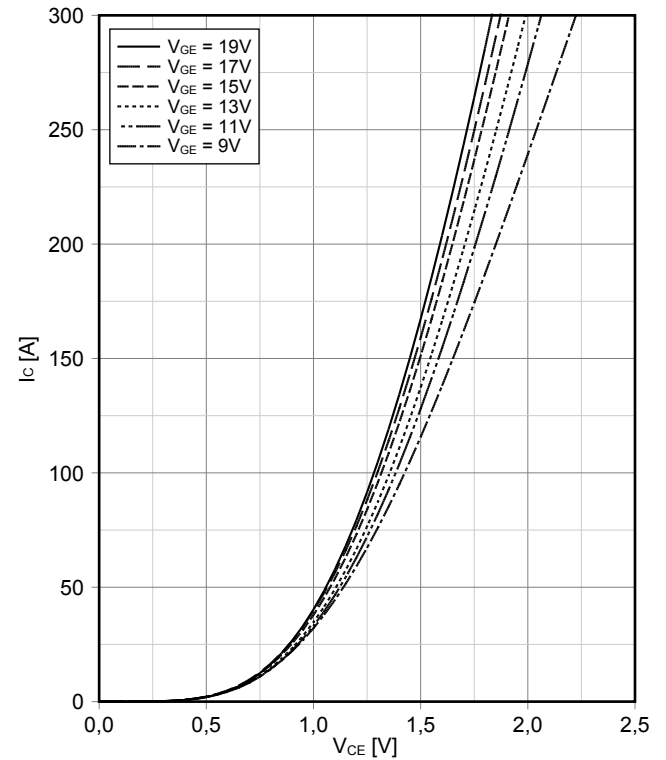
Ausgangskennlinie IGBT, T1 / T4 (typisch)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15 \text{ V}$



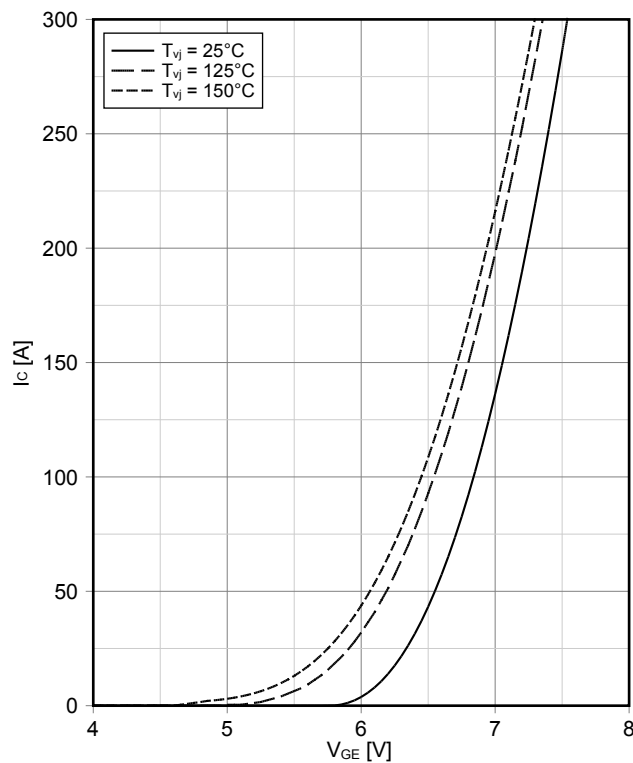
Ausgangskennlinienfeld IGBT, T1 / T4 (typisch)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



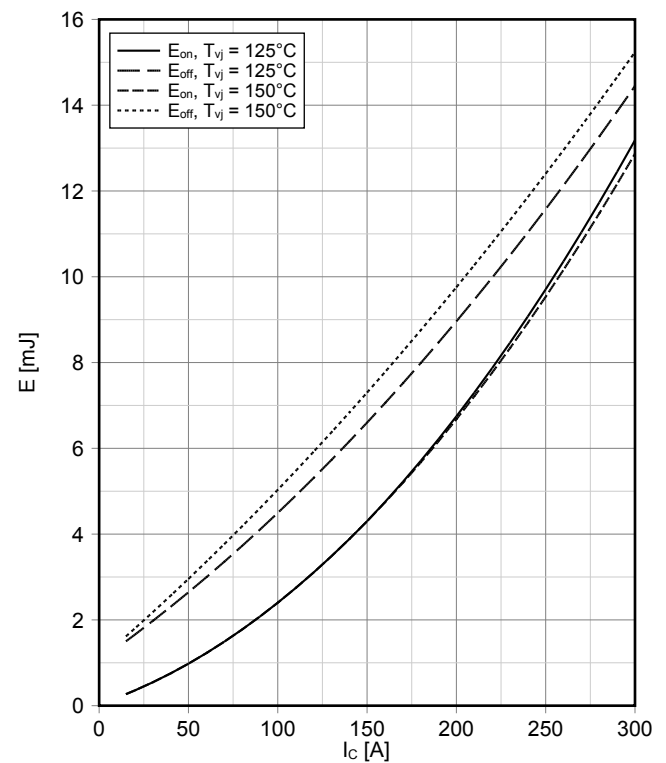
Übertragungscharakteristik IGBT, T1 / T4 (typisch)
transfer characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20 \text{ V}$



Schaltverluste IGBT, T1 / T4 (typisch)
switching losses IGBT, T1 / T4 (typical)

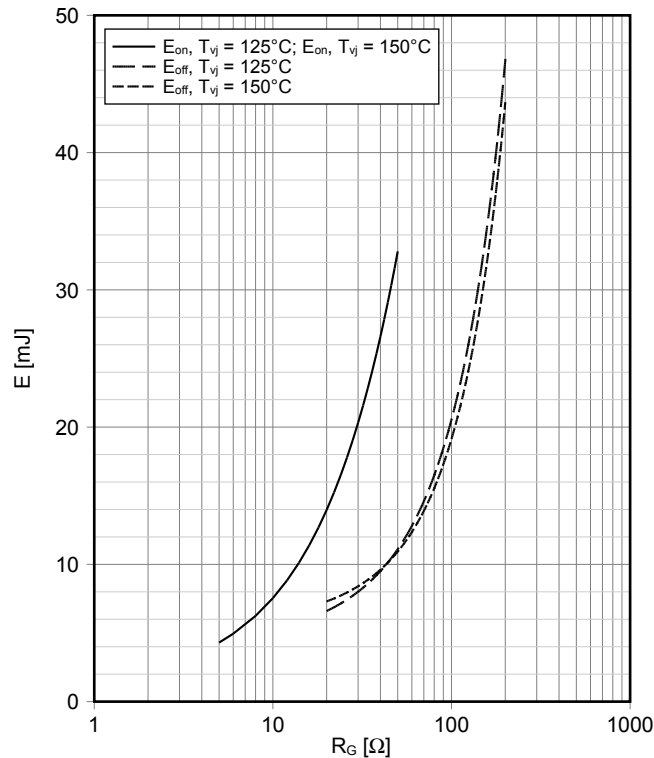
$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 20 \Omega$, $V_{CE} = 500 \text{ V}$



Schaltverluste IGBT, T1 / T4 (typisch) switching losses IGBT, T1 / T4 (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$

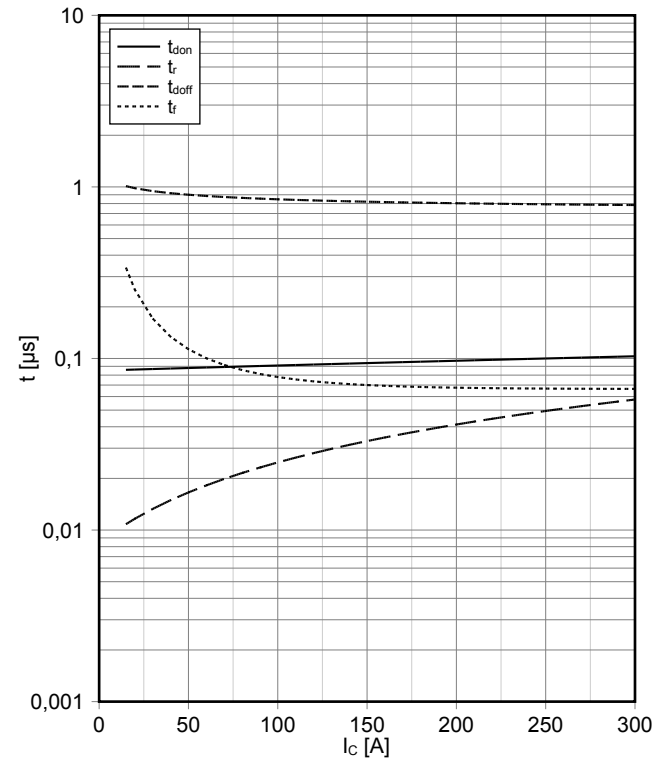
$V_{GE} = \pm 15 \text{ V}$, $I_C = 150 \text{ A}$, $V_{CE} = 500 \text{ V}$



Schaltzeiten IGBT, T1 / T4 (typisch) switching times IGBT, T1 / T4 (typical)

$t_{don} = f(I_C)$, $t_r = f(I_C)$, $t_{doff} = f(I_C)$, $t_f = f(I_C)$

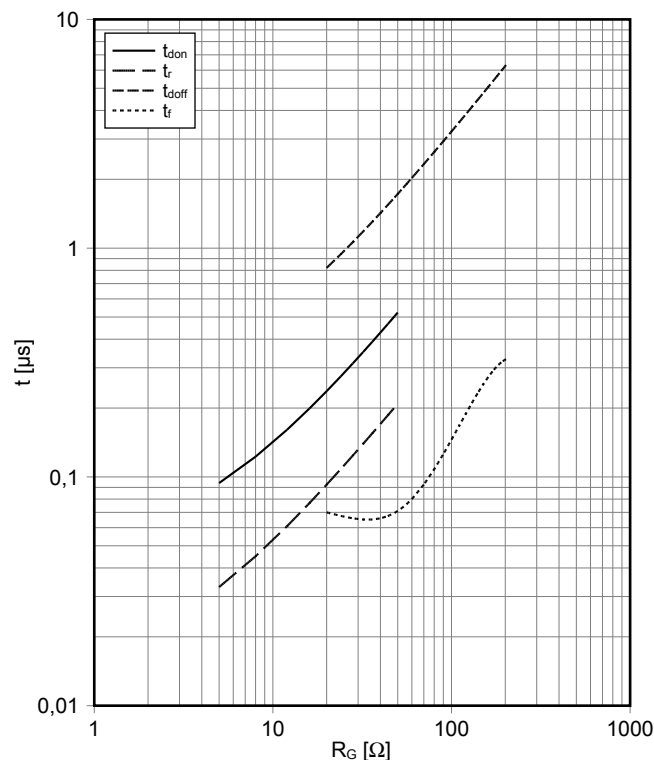
$V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 20 \Omega$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



Schaltzeiten IGBT, T1 / T4 (typisch) switching times IGBT, T1 / T4 (typical)

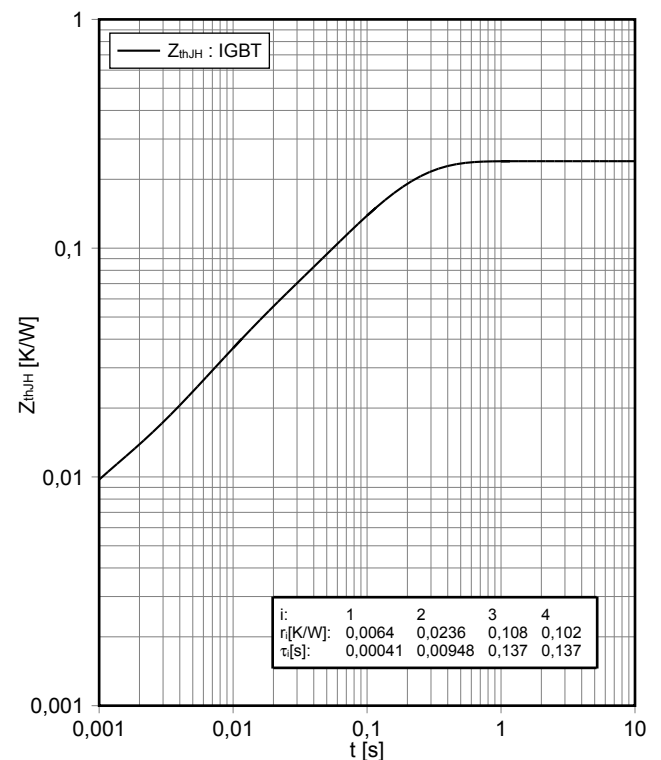
$t_{don} = f(R_G)$, $t_r = f(R_G)$, $t_{doff} = f(R_G)$, $t_f = f(R_G)$

$V_{GE} = \pm 15 \text{ V}$, $I_C = 150 \text{ A}$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



Transienter Wärmewiderstand IGBT, T1 / T4 transient thermal impedance IGBT, T1 / T4

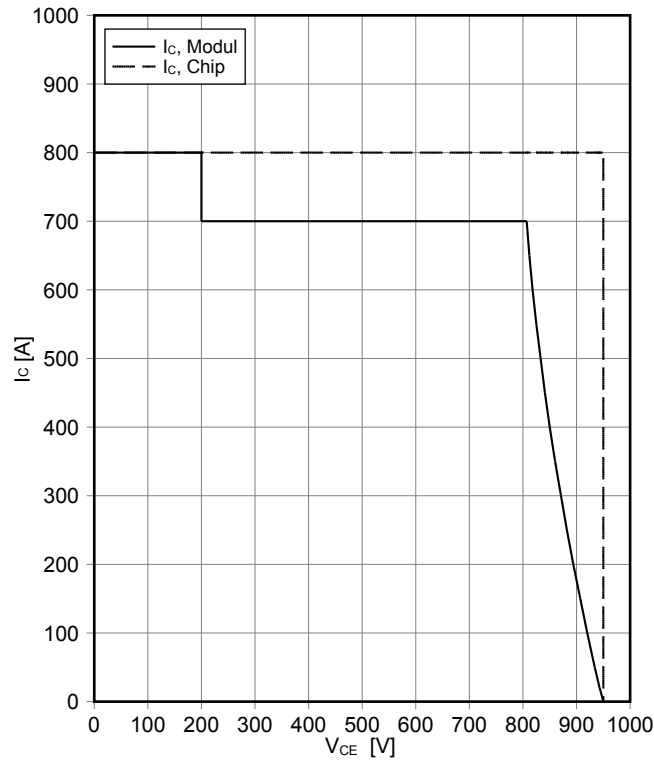
$Z_{thJH} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT, T1 / T4 (RBSOA) reverse bias safe operating area IGBT, T1 / T4 (RBSOA)

$I_C = f(V_{CE})$

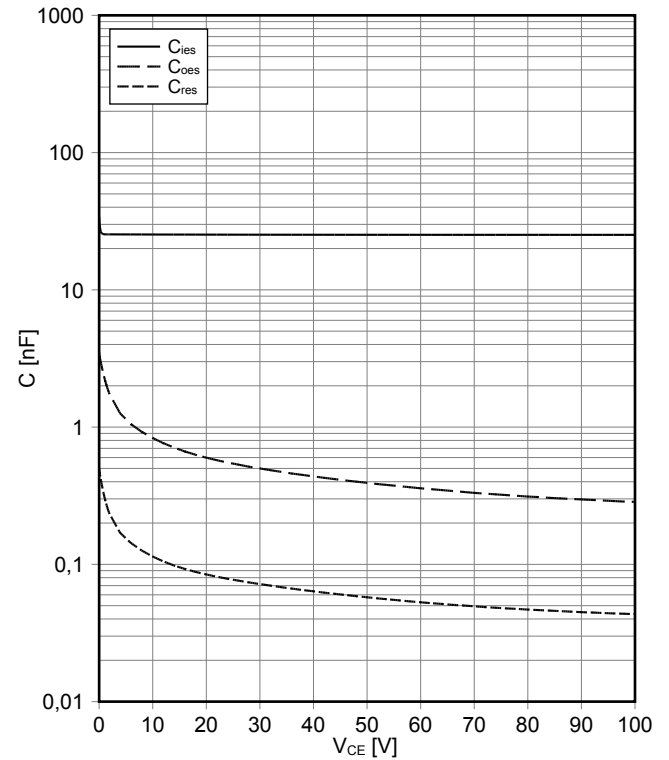
$V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 20 \Omega$, $T_{vj} = 150^\circ\text{C}$



Kapazitäts Charakteristik IGBT, T1 / T4 (typisch) capacity characteristic IGBT, T1 / T4 (typical)

$C = f(V_{CE})$

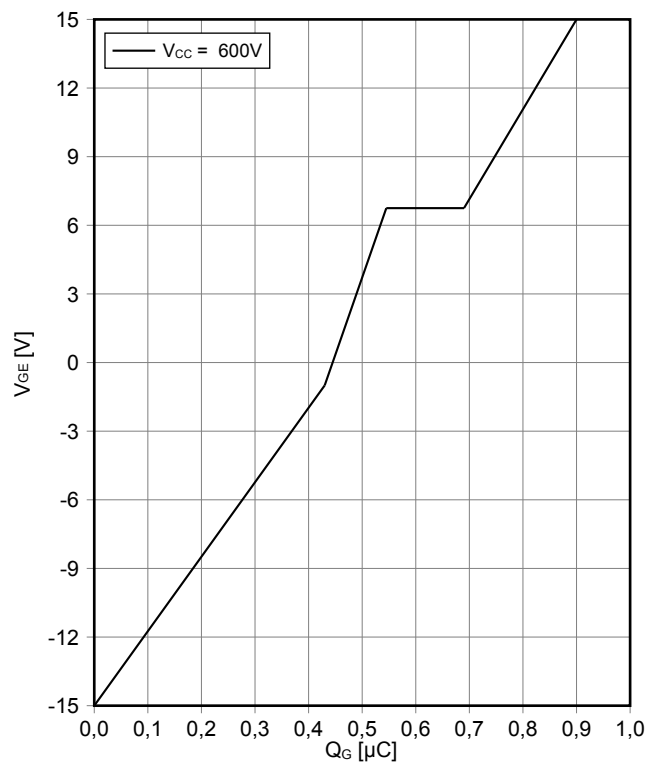
$V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



Gateladungs Charakteristik IGBT, T1 / T4 (typisch) gate charge characteristic IGBT, T1 / T4 (typical)

$V_{GE} = f(Q_G)$

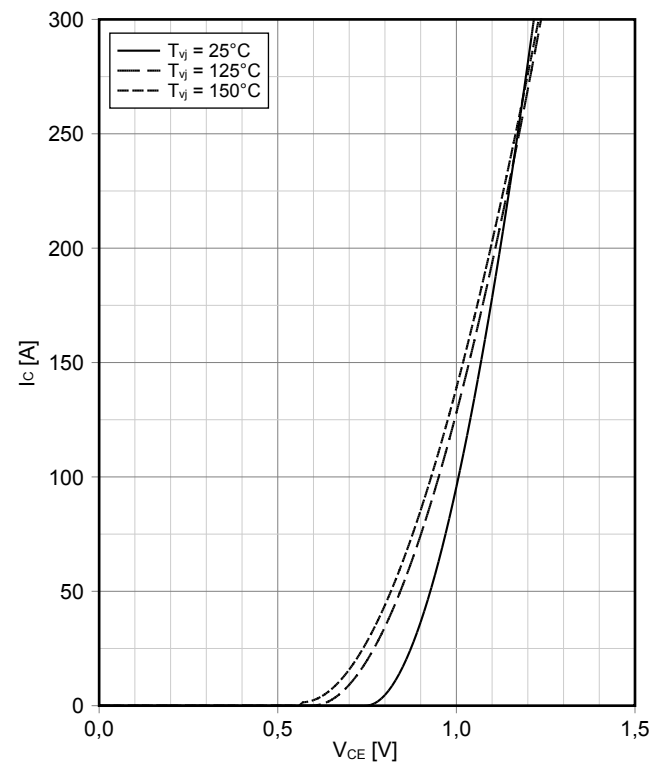
$I_C = 400 \text{ A}$, $T_{vj} = 25^\circ\text{C}$



Ausgangskennlinie IGBT, T2 / T3 (typisch) output characteristic IGBT, T2 / T3 (typical)

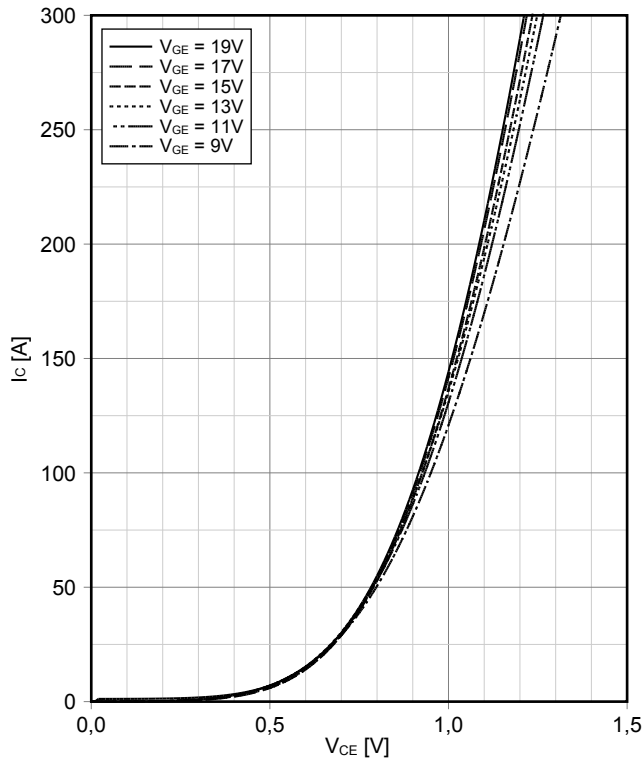
$I_C = f(V_{CE})$

$V_{GE} = 15 \text{ V}$



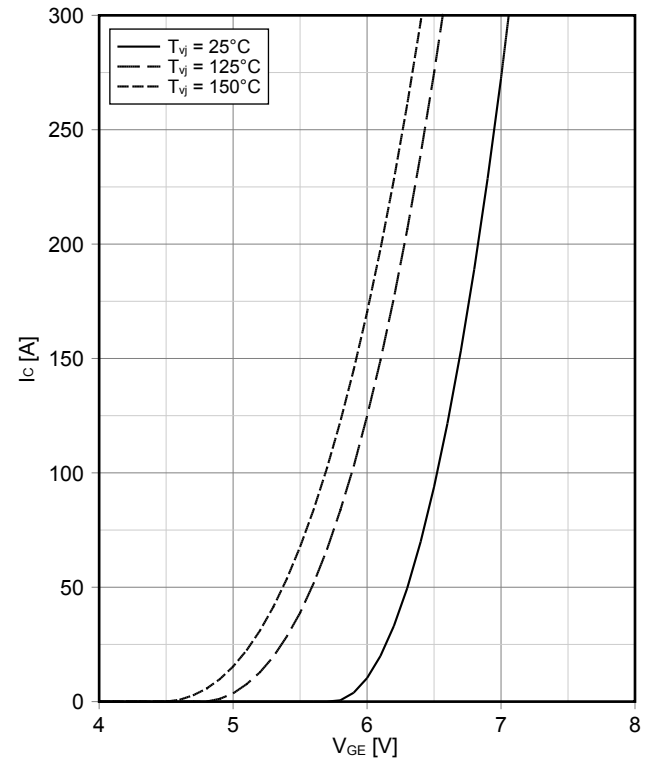
Ausgangskennlinienfeld IGBT, T2 / T3 (typisch) output characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



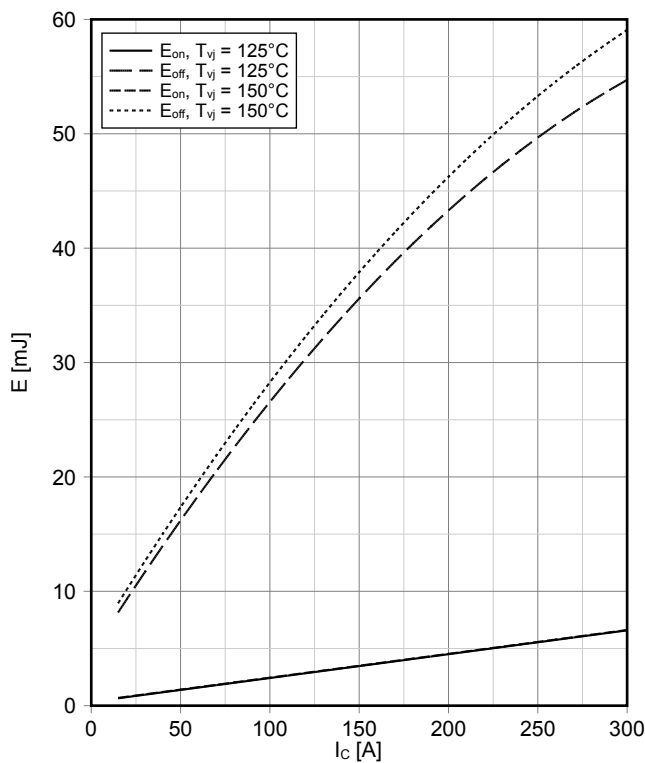
Übertragungscharakteristik IGBT, T2 / T3 (typisch) transfer characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



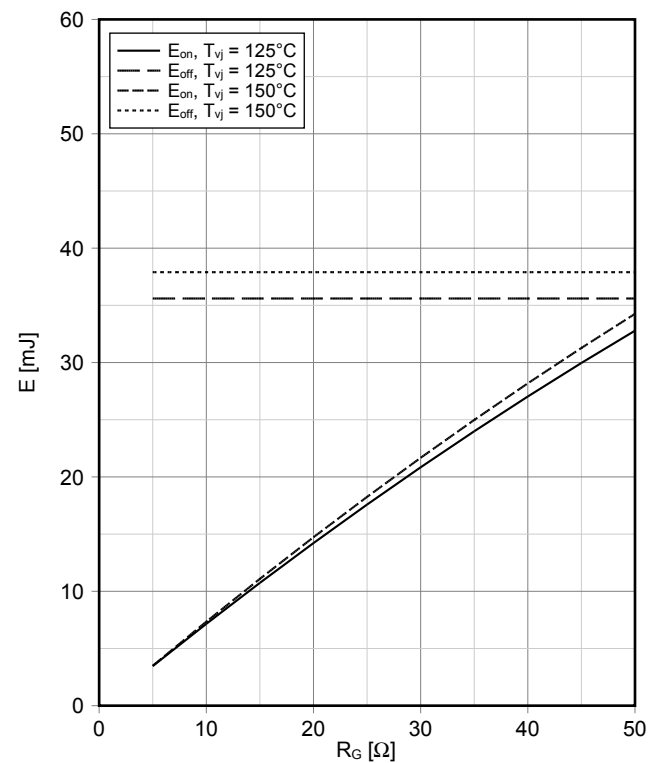
Schaltverluste IGBT, T2 / T3 (typisch) switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 5\ \Omega$, $R_{Goff} = 5\ \Omega$, $V_{CE} = 500\text{ V}$



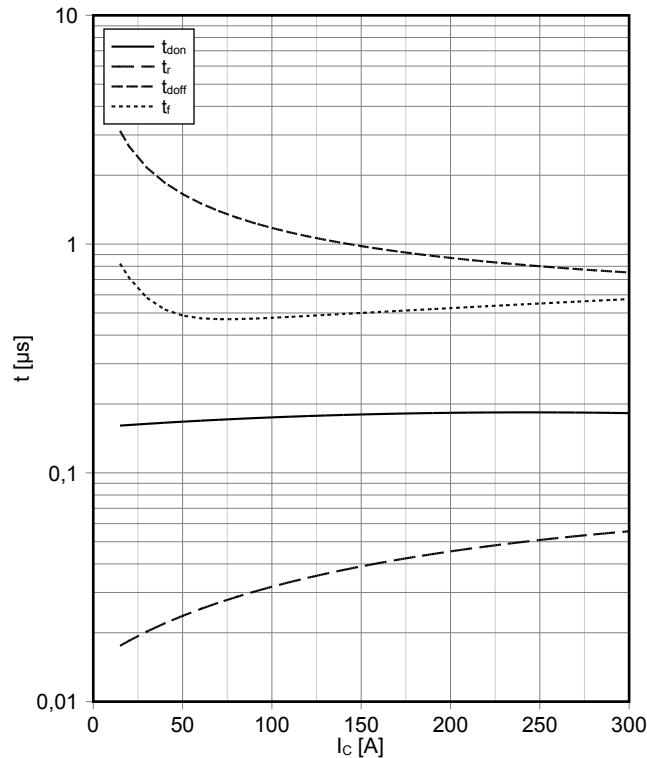
Schaltverluste IGBT, T2 / T3 (typisch) switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 150\text{ A}$, $V_{CE} = 500\text{ V}$



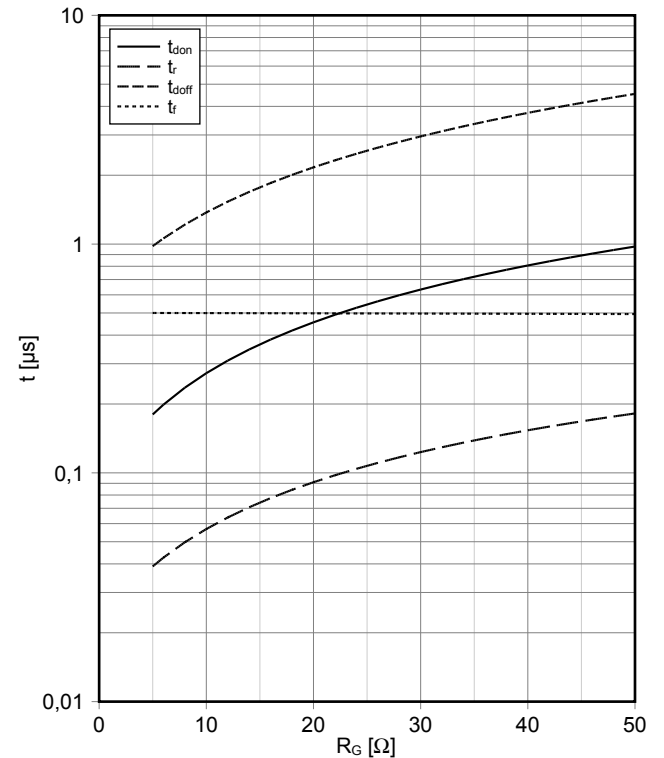
Schaltzeiten IGBT, T2 / T3 (typisch) switching times IGBT, T2 / T3 (typical)

$t_{don} = f(I_C)$, $t_r = f(I_C)$, $t_{doff} = f(I_C)$, $t_f = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 5 \Omega$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



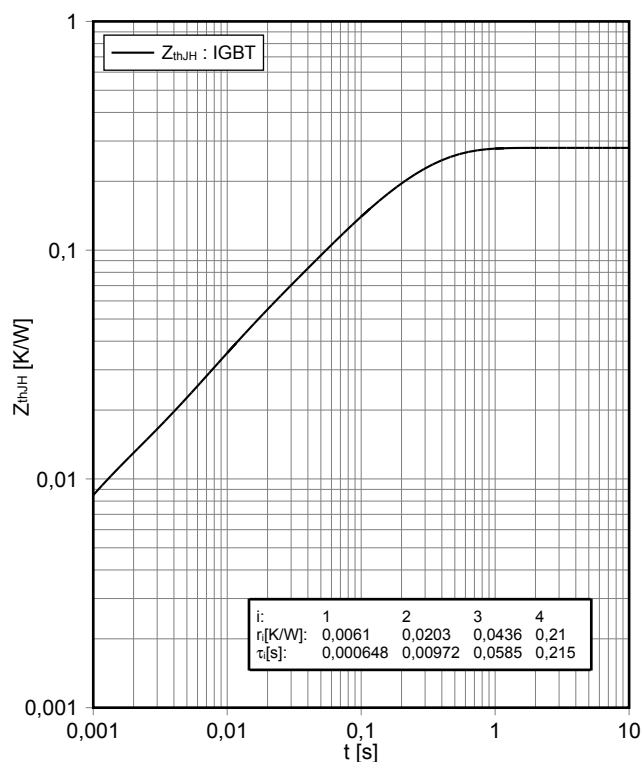
Schaltzeiten IGBT, T2 / T3 (typisch) switching times IGBT, T2 / T3 (typical)

$t_{don} = f(R_G)$, $t_r = f(R_G)$, $t_{doff} = f(R_G)$, $t_f = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}$, $I_C = 150 \text{ A}$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



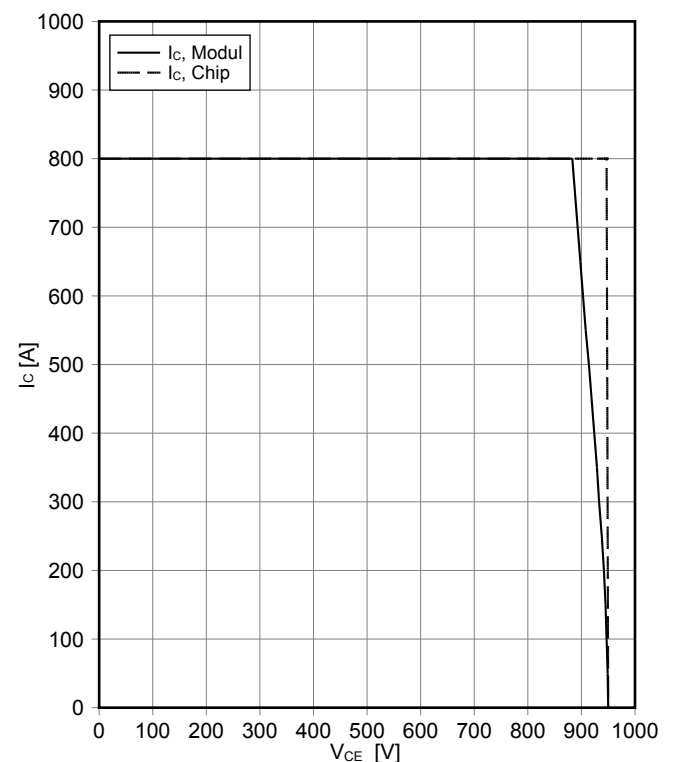
Transienter Wärmewiderstand IGBT, T2 / T3 transient thermal impedance IGBT, T2 / T3

$Z_{thJH} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT, T2 / T3 (RBSOA) reverse bias safe operating area IGBT, T2 / T3 (RBSOA)

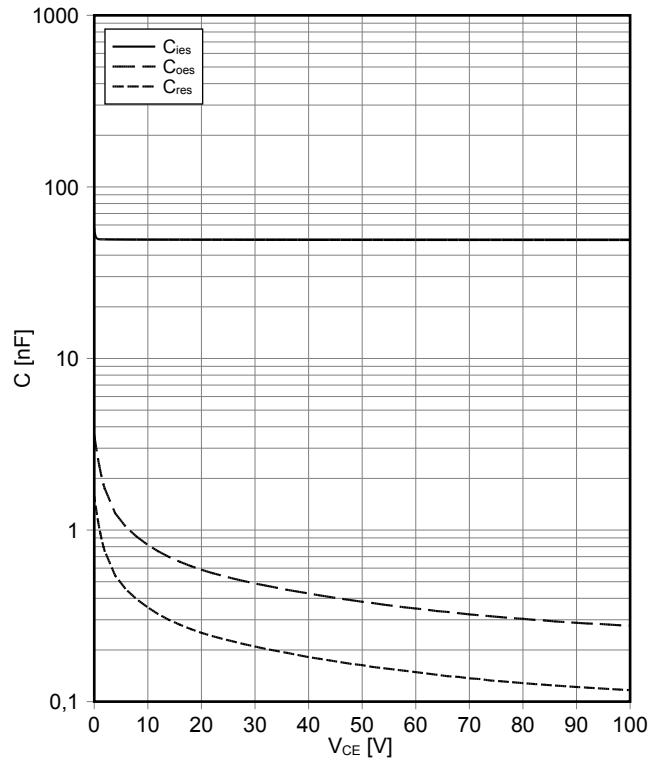
$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 5 \Omega$, $T_{vj} = 150^\circ\text{C}$



Kapazitäts Charakteristik IGBT, T2 / T3 (typisch) capacity characteristic IGBT, T2 / T3 (typical)

$$C = f(V_{CE})$$

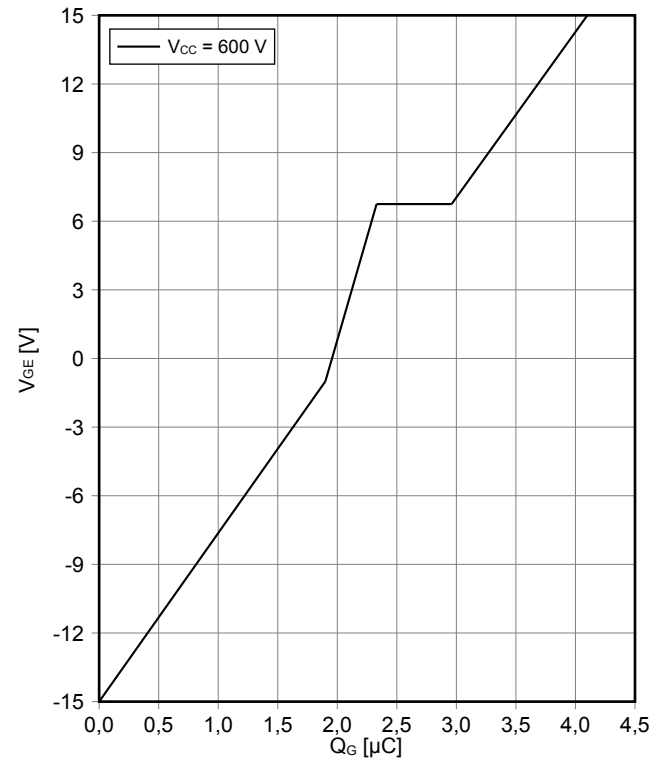
$V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



Gateladungs Charakteristik IGBT, T2 / T3 (typisch) gate charge characteristic IGBT, T2 / T3 (typical)

$$V_{GE} = f(Q_G)$$

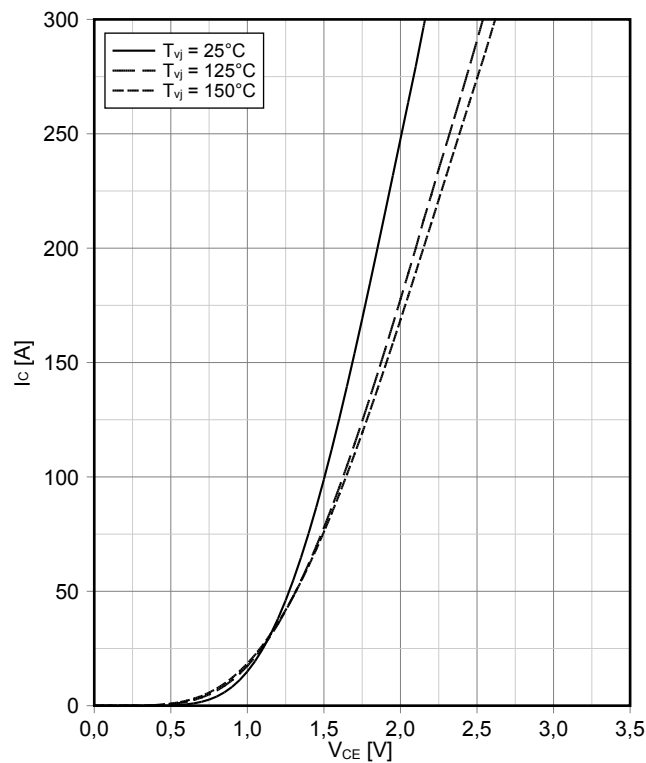
$I_C = 400 \text{ A}$, $T_{vj} = 25^\circ\text{C}$



Ausgangskennlinie IGBT, T5 / T6 (typisch) output characteristic IGBT, T5 / T6 (typical)

$$I_C = f(V_{CE})$$

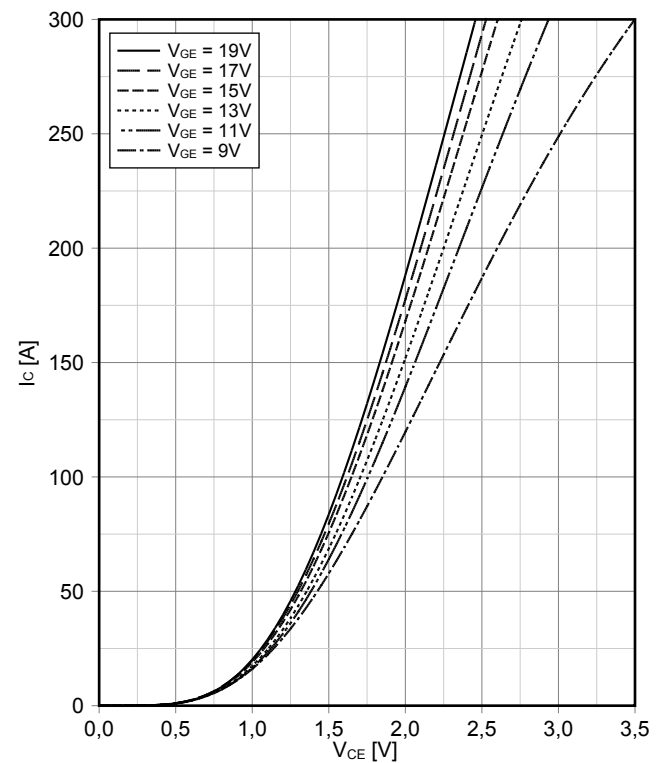
$V_{GE} = 15 \text{ V}$



Ausgangskennlinienfeld IGBT, T5 / T6 (typisch) output characteristic IGBT, T5 / T6 (typical)

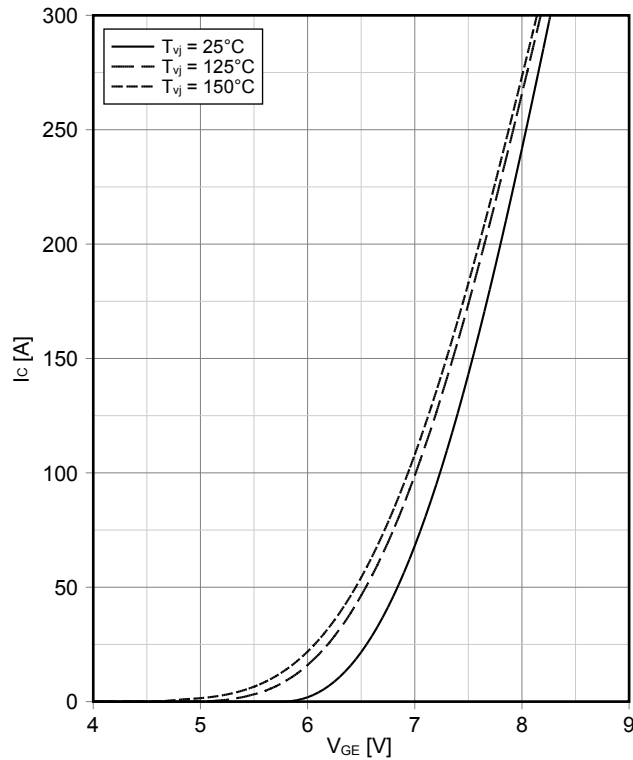
$$I_C = f(V_{CE})$$

$T_{vj} = 150^\circ\text{C}$



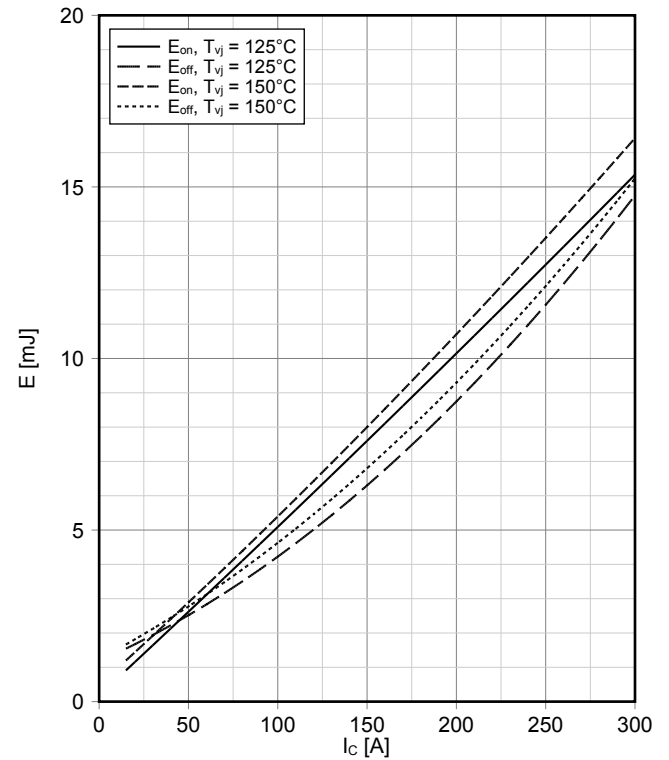
Übertragungscharakteristik IGBT, T5 / T6 (typisch) transfer characteristic IGBT, T5 / T6 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20 \text{ V}$



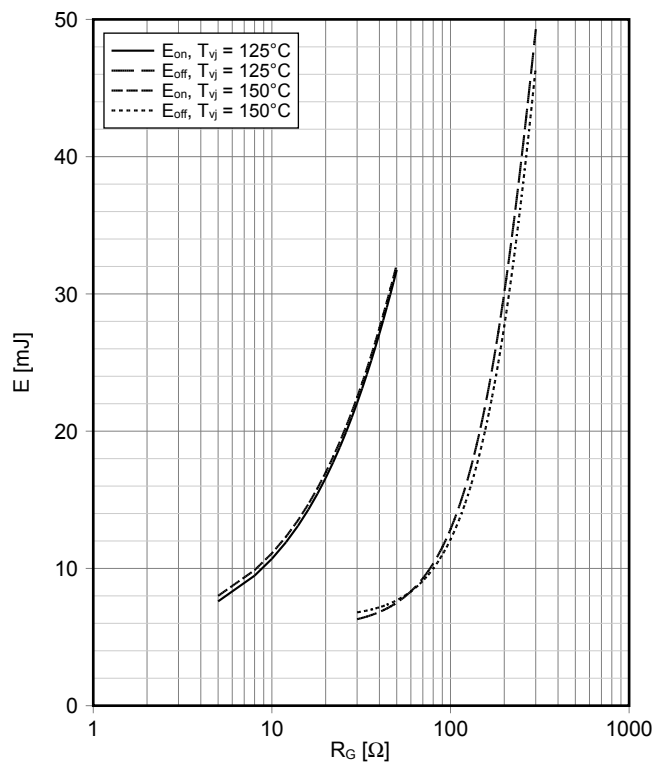
Schaltverluste IGBT, T5 / T6 (typisch) switching losses IGBT, T5 / T6 (typical)

$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 30 \Omega$, $V_{CE} = 500 \text{ V}$



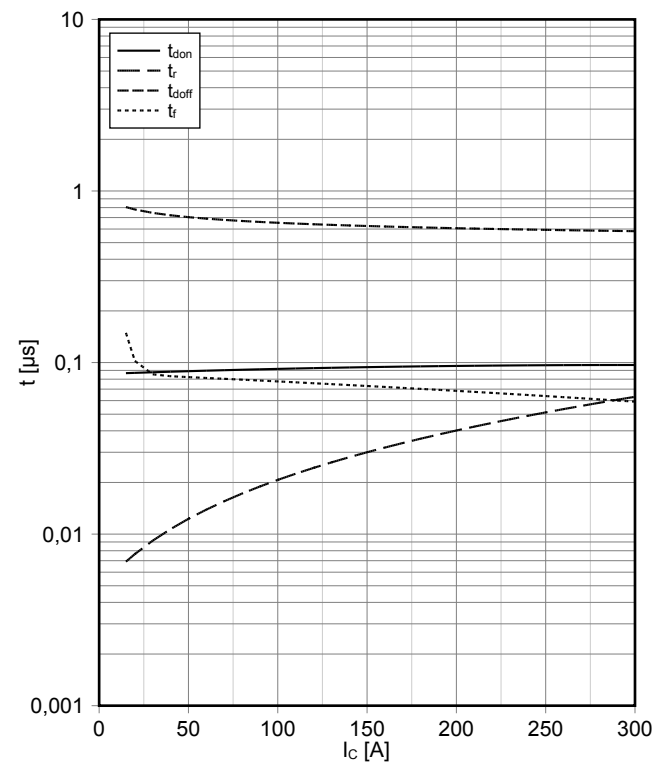
Schaltverluste IGBT, T5 / T6 (typisch) switching losses IGBT, T5 / T6 (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15 \text{ V}$, $I_C = 150 \text{ A}$, $V_{CE} = 500 \text{ V}$



Schaltzeiten IGBT, T5 / T6 (typisch) switching times IGBT, T5 / T6 (typical)

$t_{don} = f(I_C)$, $t_r = f(I_C)$, $t_{doff} = f(I_C)$, $t_f = f(I_C)$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Gon} = 5 \Omega$, $R_{Goff} = 30 \Omega$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$

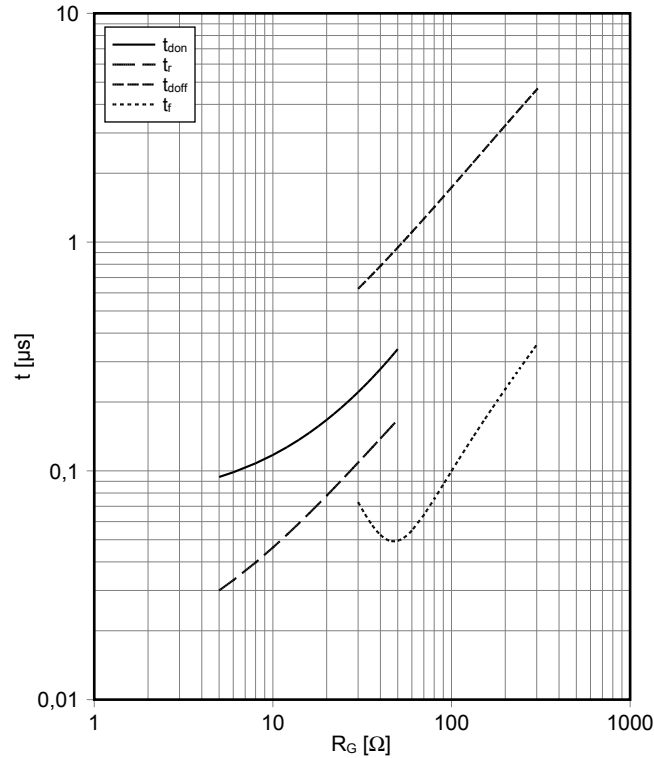


Schaltzeiten IGBT, T5 / T6 (typisch)

switching times IGBT, T5 / T6 (typical)

$t_{don} = f(R_G)$, $t_r = f(R_G)$, $t_{doff} = f(R_G)$, $t_f = f(R_G)$

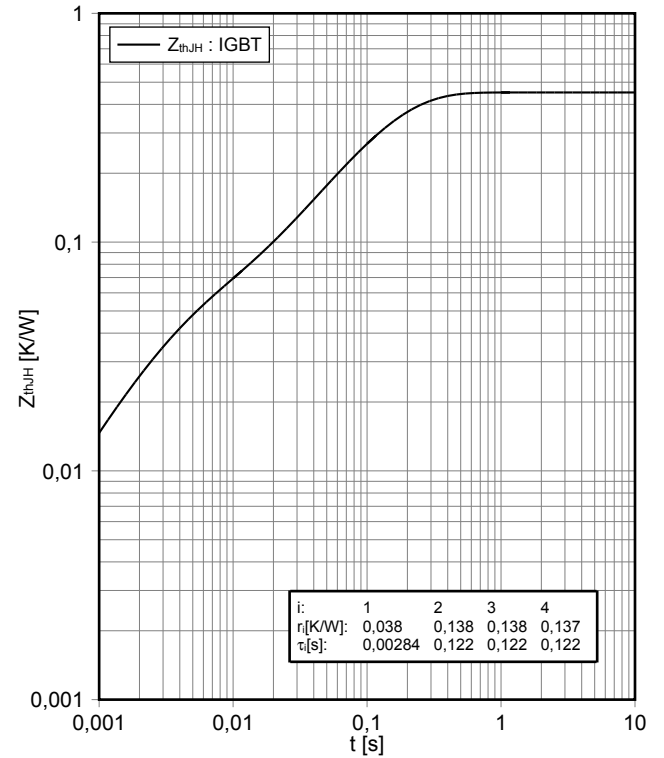
$V_{GE} = \pm 15 \text{ V}$, $I_C = 150 \text{ A}$, $V_{CE} = 500 \text{ V}$, $T_{vj} = 150^\circ\text{C}$



Transienter Wärmewiderstand IGBT, T5 / T6

transient thermal impedance IGBT, T5 / T6

$Z_{thJH} = f(t)$

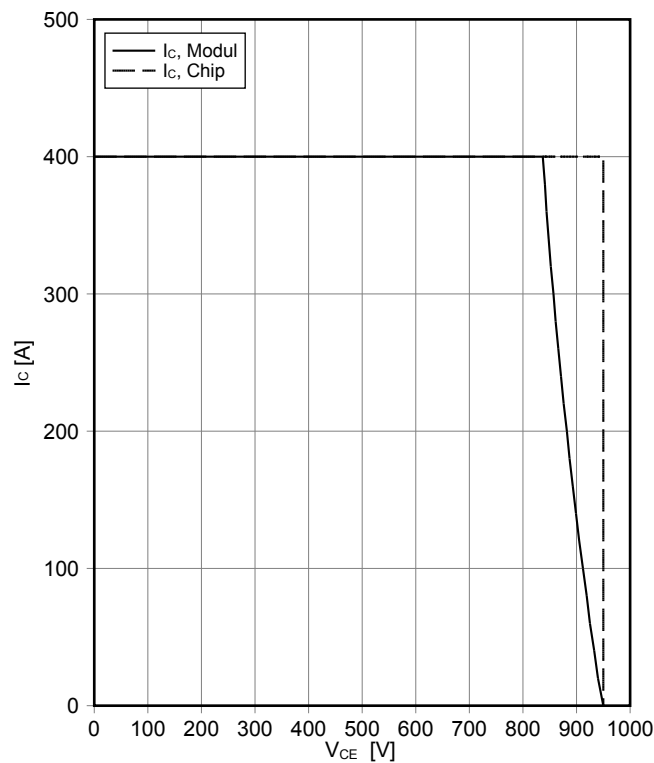


Sicherer Rückwärts-Arbeitsbereich IGBT, T5 / T6 (RBSOA)

reverse bias safe operating area IGBT, T5 / T6 (RBSOA)

$I_C = f(V_{CE})$

$V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 30 \Omega$, $T_{vj} = 150^\circ\text{C}$

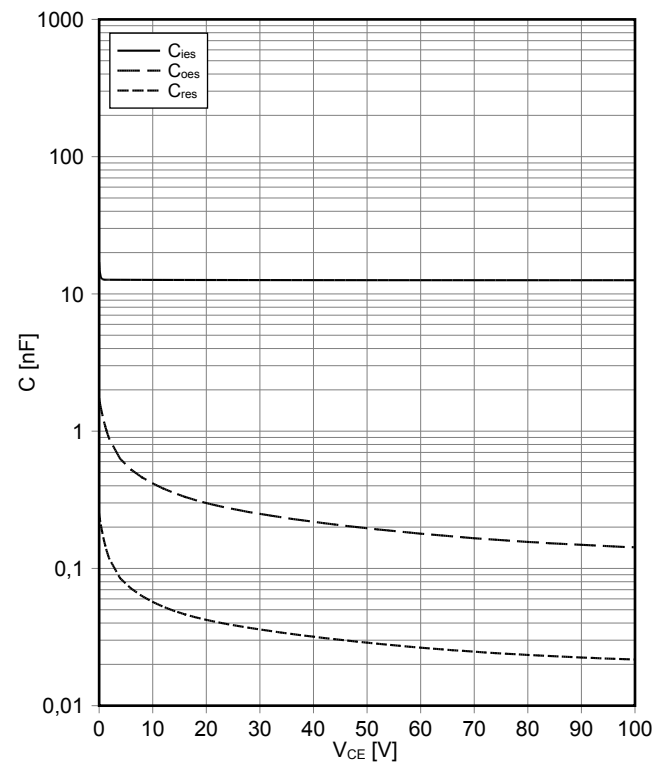


Kapazitäts Charakteristik IGBT, T5 / T6 (typisch)

capacity characteristic IGBT, T5 / T6 (typical)

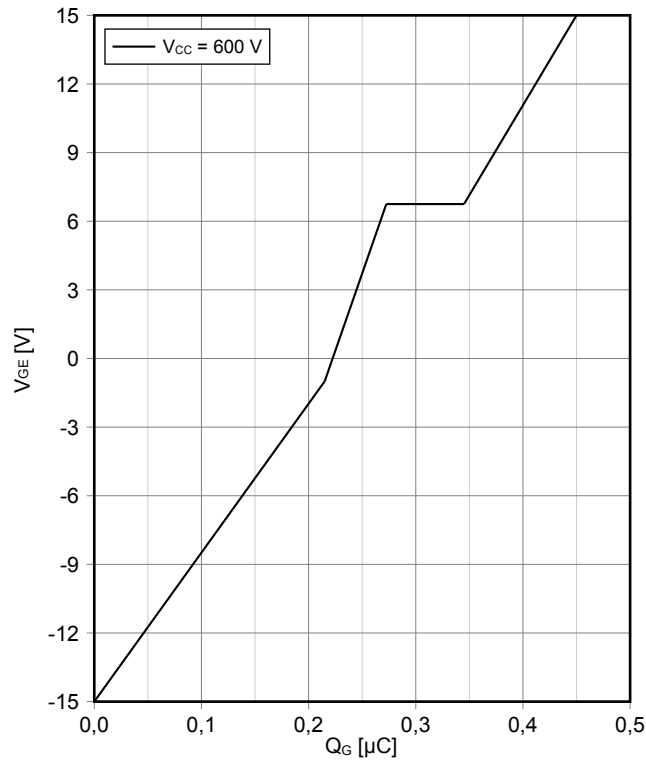
$C = f(V_{CE})$

$V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



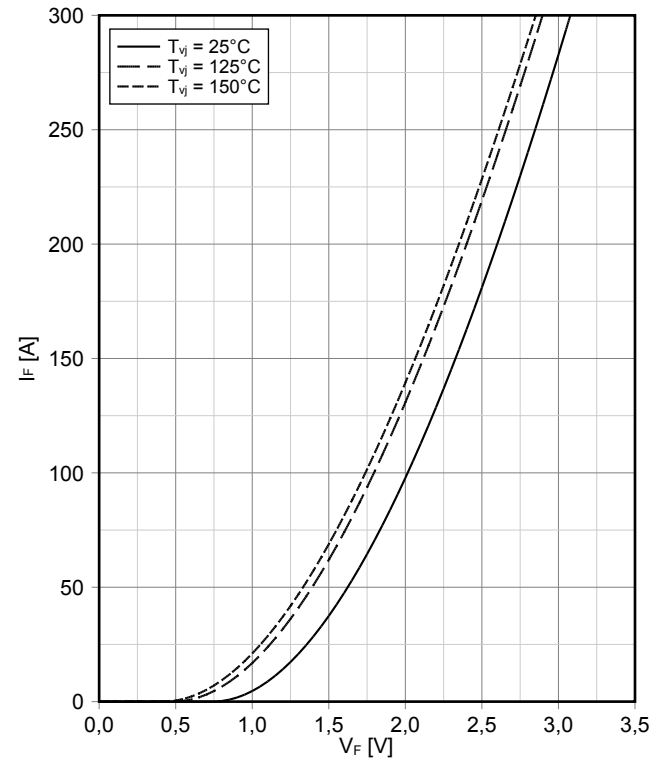
Gateladungs Charakteristik IGBT, T5 / T6 (typisch)
gate charge characteristic IGBT, T5 / T6 (typical)

$V_{GE} = f(Q_G)$
 $I_C = 200\text{ A}$, $T_{vj} = 25^\circ\text{C}$



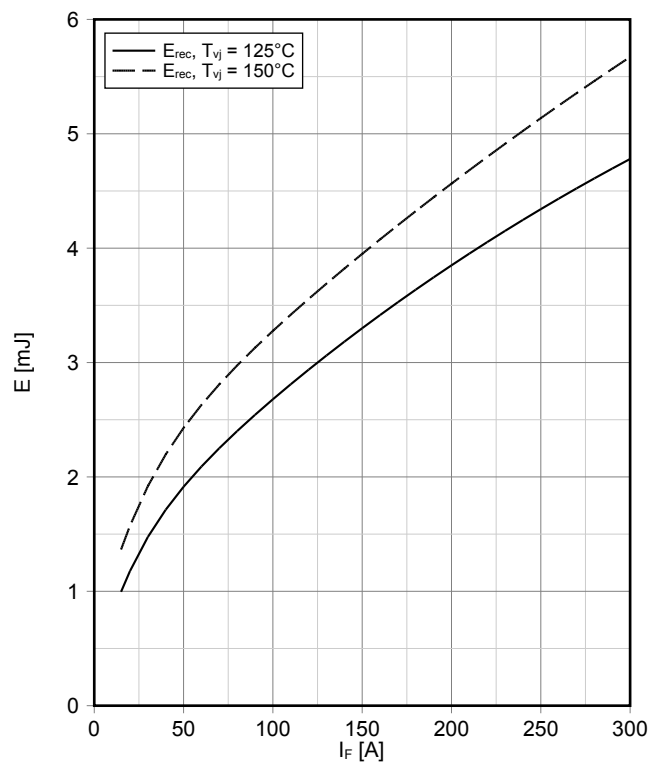
Durchlasskennlinie der Diode, D1 / D4 (typisch)
forward characteristic of Diode, D1 / D4 (typical)

$I_F = f(V_F)$



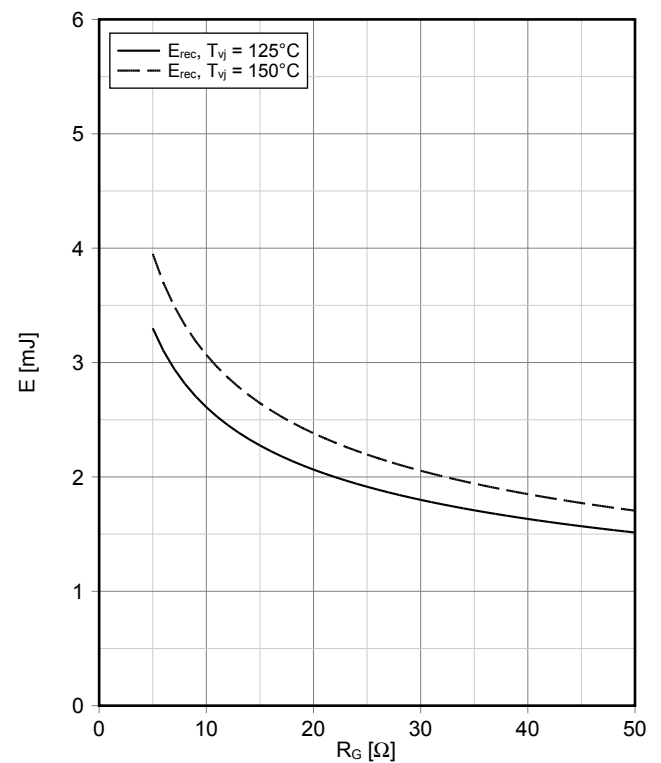
Schaltverluste Diode, D1 / D4 (typisch)
switching losses Diode, D1 / D4 (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 5\ \Omega$, $V_{CE} = 500\text{ V}$

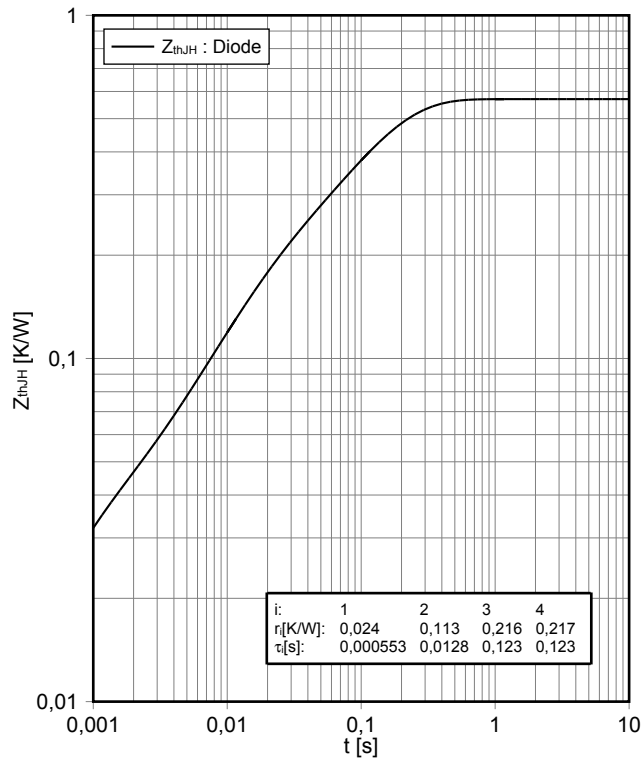


Schaltverluste Diode, D1 / D4 (typisch)
switching losses Diode, D1 / D4 (typical)

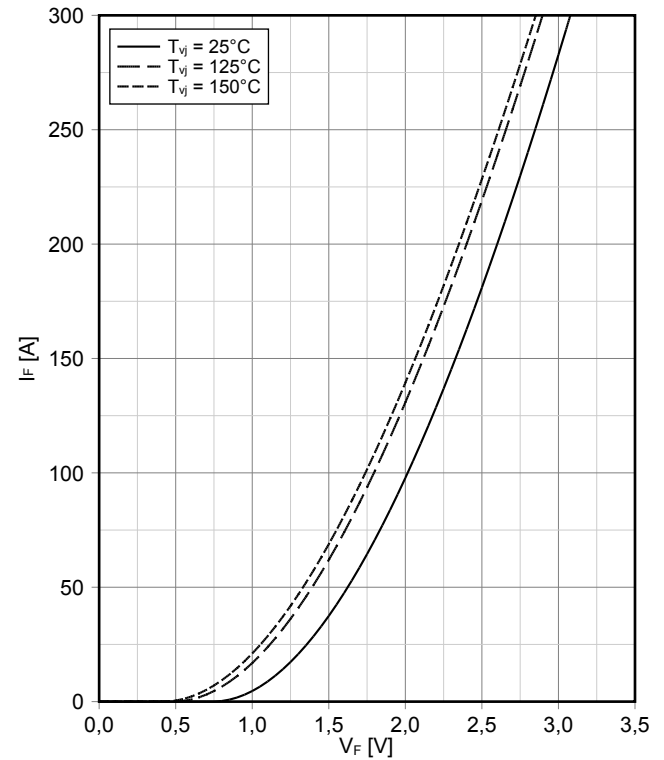
$E_{rec} = f(R_G)$
 $I_F = 150\text{ A}$, $V_{CE} = 500\text{ V}$



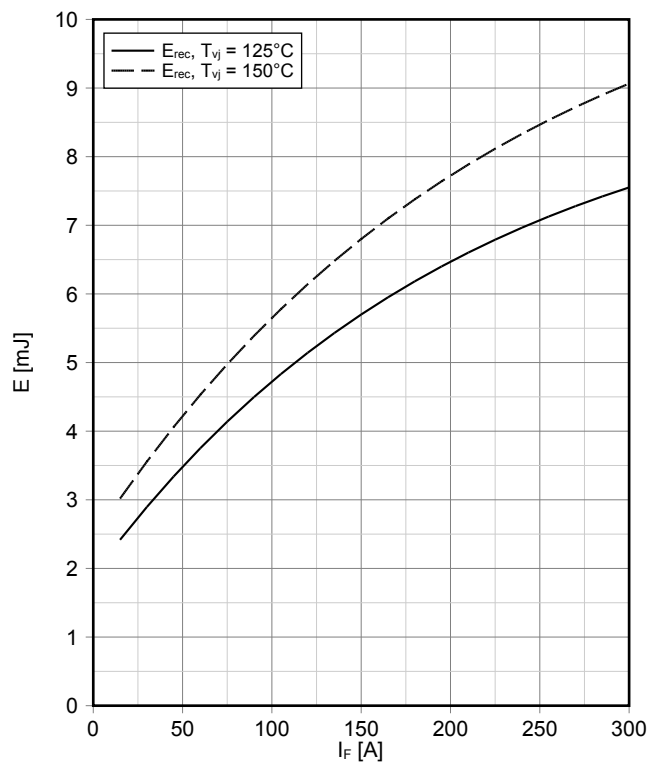
Transienter Wärmewiderstand Diode, D1 / D4
transient thermal impedance Diode, D1 / D4
 $Z_{thJH} = f(t)$



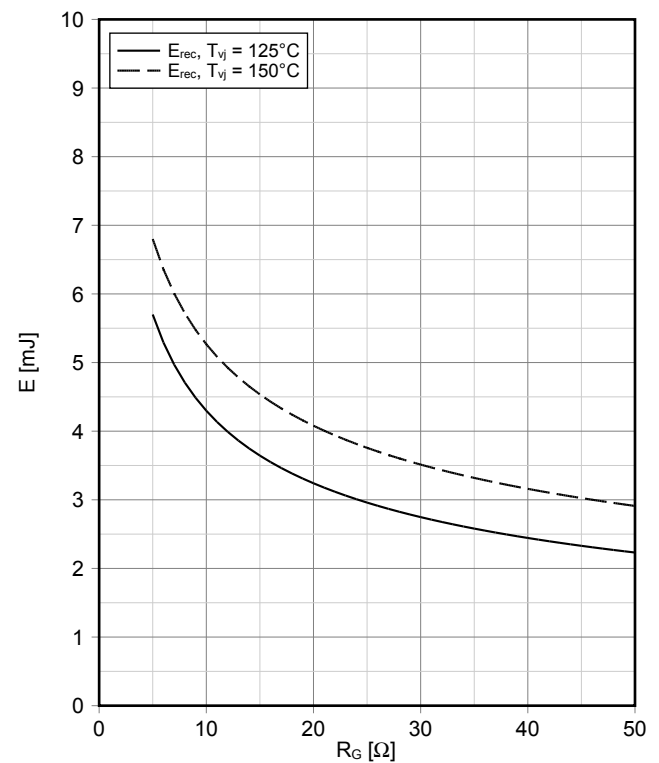
Durchlasskennlinie der Diode, D2 / D3 (typisch)
forward characteristic of Diode, D2 / D3 (typical)
 $I_F = f(V_F)$



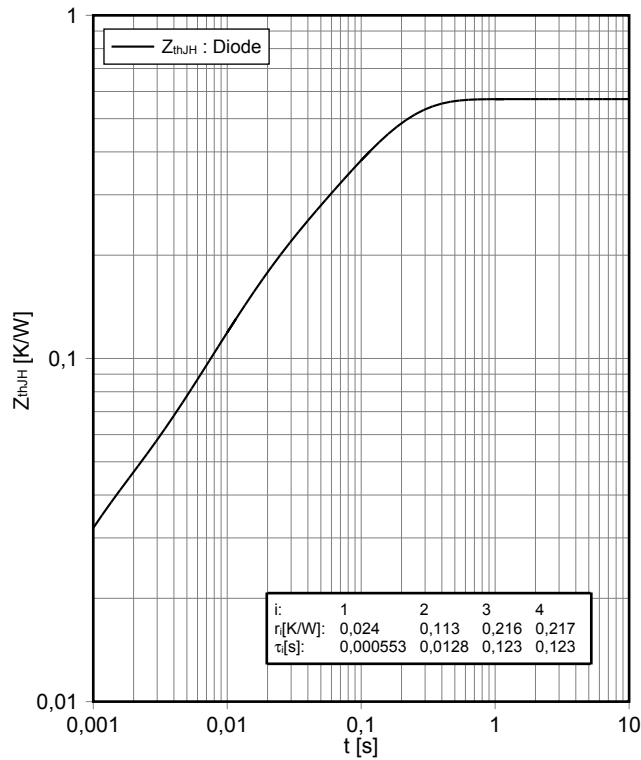
Schaltverluste Diode, D2 / D3 (typisch)
switching losses Diode, D2 / D3 (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 5 \Omega$, $V_{CE} = 500 V$



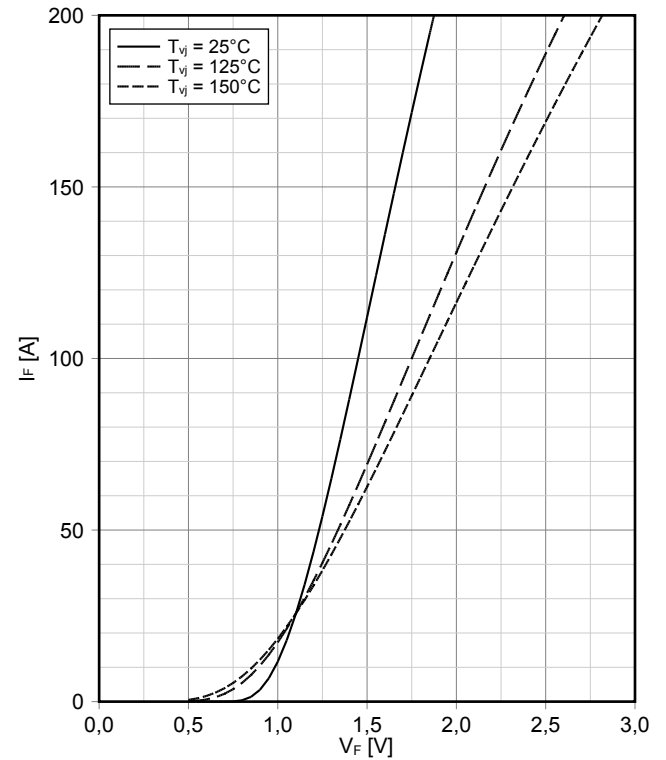
Schaltverluste Diode, D2 / D3 (typisch)
switching losses Diode, D2 / D3 (typical)
 $E_{rec} = f(R_G)$
 $I_F = 150 A$, $V_{CE} = 500 V$



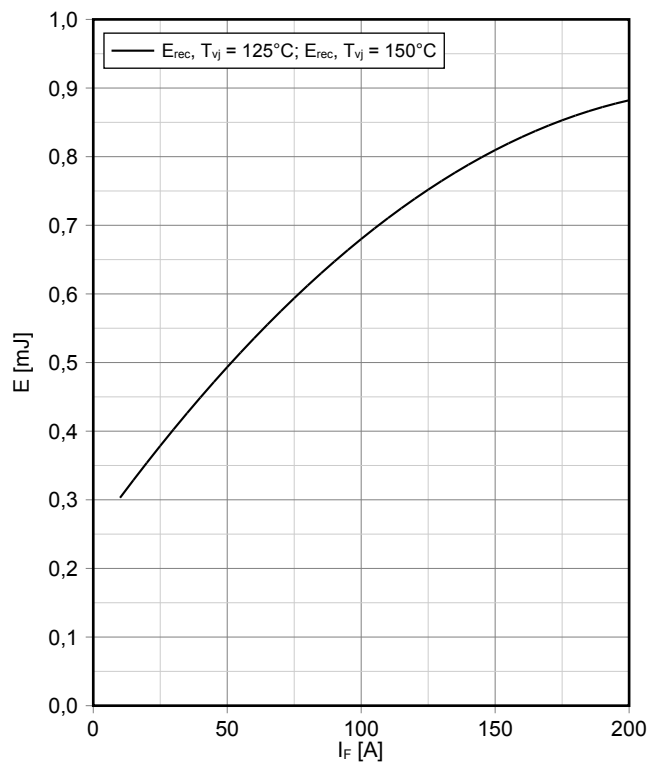
Transienter Wärmewiderstand Diode, D2 / D3
transient thermal impedance Diode, D2 / D3
 $Z_{thJH} = f(t)$



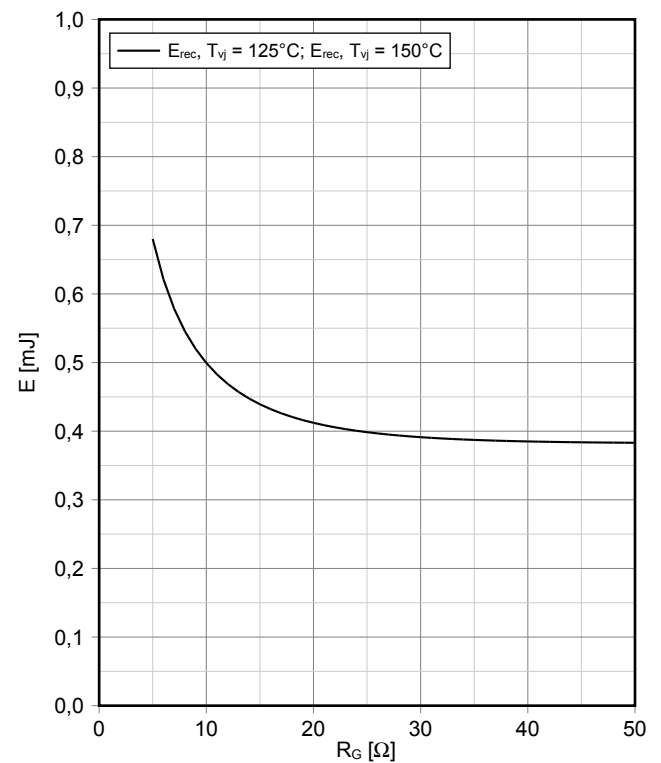
Durchlasskennlinie der Diode, D5-D6 (typisch)
forward characteristic of Diode, D5-D6 (typical)
 $I_F = f(V_F)$



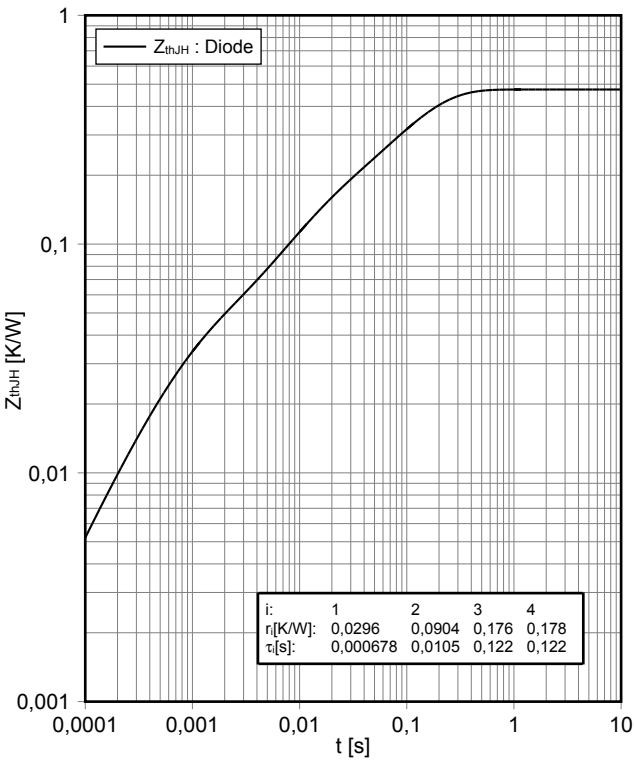
Schaltverluste Diode, D5-D6 (typisch)
switching losses Diode, D5-D6 (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 5 \Omega$, $V_{CE} = 500 V$



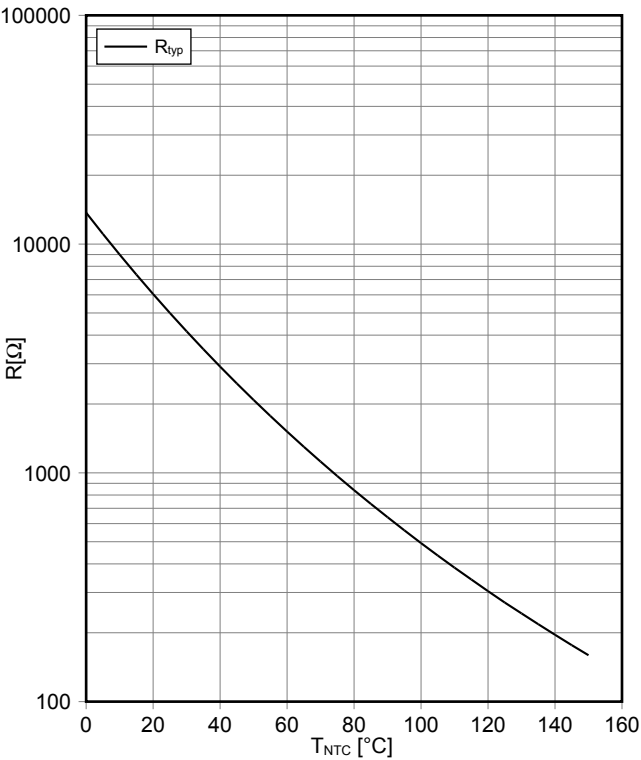
Schaltverluste Diode, D5-D6 (typisch)
switching losses Diode, D5-D6 (typical)
 $E_{rec} = f(R_G)$
 $I_F = 100 A$, $V_{CE} = 500 V$



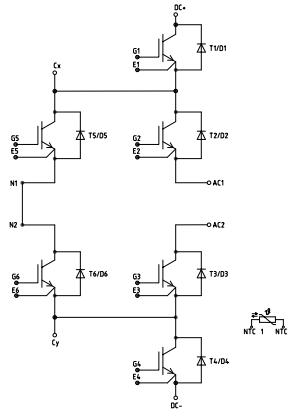
Transienter Wärmewiderstand Diode, D5-D6
transient thermal impedance Diode, D5-D6
 $Z_{thJH} = f(t)$



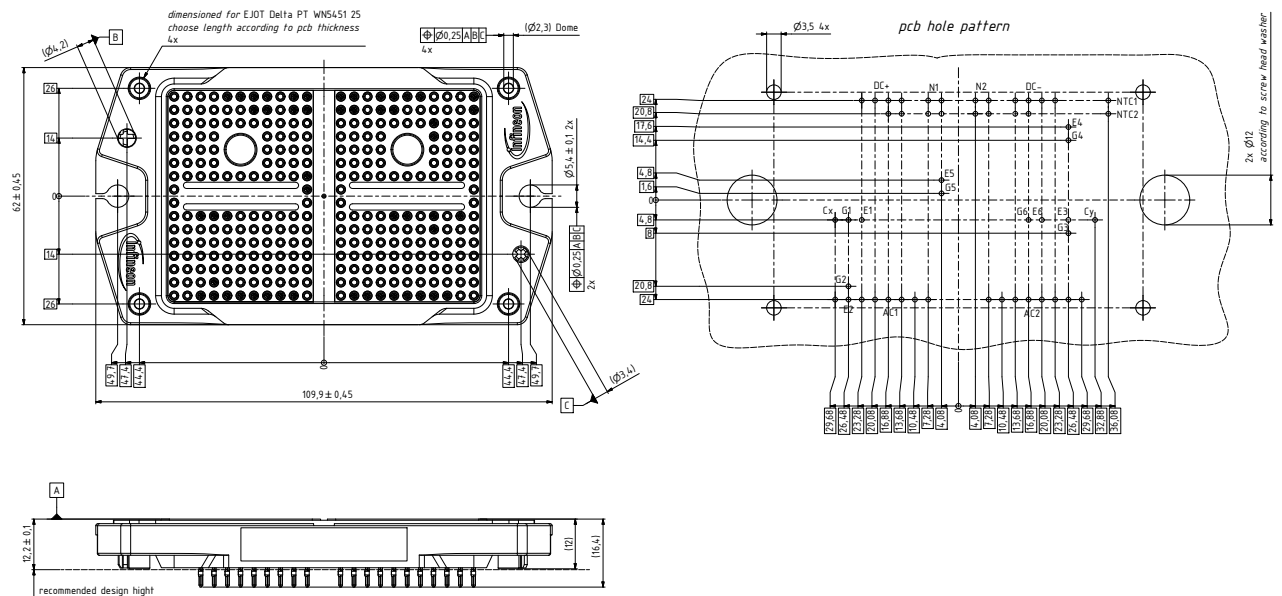
NTC-Widerstand-Temperaturkennlinie (typisch)
NTC-Thermistor-temperature characteristic (typical)
 $R = f(T)$



Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



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